

EIA/IPC/JEDEC
J-STD-002F
2026 June

JOINT INDUSTRY STANDARD

Solderability Tests
for Component
Leads, Terminations,
Lugs, Terminals and
Conductors



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EIA/IPC/JEDEC J-STD-002F

Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Conductors

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A joint standard developed by IPC Component and Wire Solderability Specification Task Group (5-23b) of the Assembly and Joining Processes Committee (5-20), the Electronic Components Industry Association Soldering Technology Committee (STC) and the JEDEC Solid State Technology Association Committee (JC14.1)

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Woven Glass Reinforcement Task Group (3-12d) of the Printed Board Base Materials Committee (3-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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Special thank you to Gerard O'Brien and Ernst Eggelaar for their leadership, Electronic Components Industry Association Soldering Technology Committee (STC) and the JEDEC Solid State Technology Association Committee (JC14.1) for providing support for the release of this document.

For a complete list of acknowledgments:
www.electronics.org/acknowledgements-page

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